

	U	1	Document ID	Issue Date	Pages	Title	Current OR
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20030204826 A1	20031030	25	Inspection method and inspection system using charged particle beam	716/4
2	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030164460 A1	20030904	19	Patterned wafer inspection method and apparatus therefor	250/492.3
3	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030155508 A1	20030821	28	Workpiece holder, semiconductor fabricating apparatus, semiconductor inspecting apparatus, circuit pattern inspecting apparatus, charged particle beam application apparatus, calibrating substrate, workpiece holding method, circuit pattern inspecting method, and charged particle beam application method	250/310
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030146382 A1	20030807	28	Workpiece holder, semiconductor fabricating apparatus, semiconductor inspecting apparatus, circuit pattern inspecting apparatus, charged particle beam application apparatus, calibrating substrate, workpiece holding method, circuit pattern inspecting method, and charged particle beam application method	250/310
5	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030118149 A1	20030626	28	Defect inspection apparatus and defect inspection method	378/58
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030111616 A1	20030619	28	Workpiece holder, semiconductor fabricating apparatus, semiconductor inspecting apparatus, circuit pattern inspecting apparatus, charged particle beam application apparatus, calibrating substrate, workpiece holding method, circuit pattern inspecting method, and charged particle beam application method	250/492.2

	Current XRef	Retrieval Classif	Inv ntor	S	C	P	2	3	4	5
1	716/19		Nishiyama, Hidetoshi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2			Shinada, Hiroyuki et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3			Suzuki, Hiroyuki et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4	250/252.1		Suzuki, Hiroyuki et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5			Okuda, Hirohito et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6	250/442.11		Suzuki, Hiroyuki et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

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1	US 20030204826	<input type="checkbox"/>
2	US 20030164460	<input type="checkbox"/>
3	US 20030155508	<input type="checkbox"/>
4	US 20030146382	<input type="checkbox"/>
5	US 20030118149	<input type="checkbox"/>
6	US 20030111616	<input type="checkbox"/>

	U	1	Document ID	Issue Dat	Pages	Title	Current OR
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030094572 A1	20030522	21	Inspection system and inspection process for wafer with circuit using charged-particle beam	250/310
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030076989 A1	20030424	27	Automated repetitive array microstructure defect inspection	382/145
9	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030057971 A1	20030327	20	Inspection method using a charged particle beam and inspection device based thereon	324/751
10	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20030003611 A1	20030102	21	Apparatus and methods for monitoring self-aligned contact arrays	438/16
11	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20020148961 A1	20021017	104	Electron beam apparatus and device production method using the electron beam apparatus	250/311
12	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20020117635 A1	20020829	19	PATTERNED WAFER INSPECTION METHOD AND APPARATUS THEREFOR	250/492.3
13	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20020070738 A1	20020613	24	Semiconductor device inspecting apparatus	324/751
14	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20020028399 A1	20020307	102	Inspection system by charged particle beam and method of manufacturing devices using the system	430/30
15	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20020024021 A1	20020228	27	Method and apparatus for inspecting patterns of a semiconductor device with an electron beam	250/492.3
16	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20010016938 A1	20010823	25	Inspection method and inspection system using charged particle beam	716/21
17	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6614244 B2	20030902	23	Semiconductor device inspecting apparatus	324/751
18	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6512227 B2	20030128	25	Method and apparatus for inspecting patterns of a semiconductor device with an electron beam	250/310

	Current XRef	Retrieval Classif	Inventor	S	C	P	2	3	4	5
7	250/306		Matsui, Miyako et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8			Maayah, Kais Jameel et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9			Nishiyama, Hidetoshi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10			Weiner, Kurt H. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
11			Nakasuji, Mamoru et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
12			SHINADA, HIROYUKI et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
13	250/310		Yamada, Keizo et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
14	250/306; 356/237.5; 430/296		Nakasuji, Mamoru et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
15			Iwabuchi, Yuko et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
16	716/4		Nishiyama, Hidetoshi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
17			Yamada, Keizo et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
18			Iwabuchi, Yuko et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

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7	US 20030094572	<input type="checkbox"/>
8	US 20030076989	<input type="checkbox"/>
9	US 20030057971	<input type="checkbox"/>
10	US 20030003611	<input type="checkbox"/>
11	US 20020148961	<input type="checkbox"/>
12	US 20020117635	<input type="checkbox"/>
13	US 20020070738	<input type="checkbox"/>
14	US 20020028399	<input type="checkbox"/>
15	US 20020024021	<input type="checkbox"/>
16	US 20010016938	<input type="checkbox"/>
17	US 6614244	<input type="checkbox"/>
18	US 6512227	<input type="checkbox"/>

	U	1	Document ID	Issue Date	Pages	Title	Current OR
19	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6509564 B1	20030121	30	WORKPIECE HOLDER, SEMICONDUCTOR FABRICATING APPARATUS, SEMICONDUCTOR INSPECTING APPARATUS, CIRCUIT PATTERN INSPECTING APPARATUS, CHARGED PARTICLE BEAM APPLICATION APPARATUS, CALIBRATING SUBSTRATE, WORKPIECE HOLDING METHOD, CIRCUIT PATTERN INSPECTING METHOD, AND CHARGED PARTICLE BEAM APPLICATION METHOD	250/310
20	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6465783 B1	20021015	22	High-throughput specimen-inspection apparatus and methods utilizing multiple parallel charged particle beams and an array of multiple secondary-electron-dete ctors	250/311
21	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6452677 B1	20020917	20	Method and apparatus for detecting defects in the manufacture of an electronic device	356/394
22	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US RE33193 E	19900403	21	Ion beam processing apparatus and method of correcting mask defects	250/309
23	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 4761607 A	19880802	13	Apparatus and method for inspecting semiconductor devices	324/752
24	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 4503329 A	19850305	19	Ion beam processing apparatus and method of correcting mask defects	250/309
25	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 4357540 A	19821102	10	Semiconductor device array mask inspection method and apparatus	250/491.1

	Current XRef	Retrieval Classif	Inventor	S	C	P	2	3	4	5
19	250/491.1		Suzuki, Hiroyuki et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
20	250/306; 250/307; 250/310		Nakasuji, Mamoru	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
21	250/307; 250/310; 356/237.3; 356/237.4; 356/388		Do, Douglas et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
22	250/492.2		Yamaguchi, Hiroshi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
23	324/765; 714/724; 714/732		Shiragasawa, Tsuyoshi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
24	250/492.2; 257/E21.21 1		Yamaguchi, Hiroshi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
25	250/492.2		Benjamin, Charles E. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>



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19	US 6509564	<input type="checkbox"/>
20	US 6465783	<input type="checkbox"/>
21	US 6452677	<input type="checkbox"/>
22	US RE33193	<input type="checkbox"/>
23	US 4761607	<input type="checkbox"/>
24	US 4503329	<input type="checkbox"/>
25	US 4357540	<input type="checkbox"/>

	Type	L #	Hits	S arch Text	DBs	Time Stamp	Comments
1	IS&R	L1	0	("(electron or (charged adj particle) near3 beam\$2)) and (semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5) ".PN.	USPA T; US-P GPUB	2004/03/08 11:26	
2	BRS	L2	34	(electron or (charged adj particle) near3 beam\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5))	USPA T; US-P GPUB	2004/03/08 11:34	
3	BRS	L3	0	L2 and (compar\$5 with ((defective or damaged) near2 (chip or circuit or device or die)))	USPA T; US-P GPUB	2004/03/08 11:29	
4	BRS	L4	1	L2 and (compar\$5 with (defective or damaged))	USPA T; US-P GPUB	2004/03/08 11:36	
5	BRS	L5	34	(electron or (charged adj particle) near3 (beam\$2 or irradiation)) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5))	USPA T; US-P GPUB	2004/03/08 11:35	
6	BRS	L7	1	L6 and (compar\$5 with (defective or damaged).)	USPA T; US-P GPUB	2004/03/08 11:37	
7	BRS	L8	1	20020130262.pn.	USPA T; US-P GPUB	2004/03/08 11:37	
8	BRS	L9	1	L7 and (compar\$5 with (defective or damaged))	USPA T; US-P GPUB	2004/03/08 11:39	
9	BRS	L6	8	(secondary adj electron\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5))	USPA T; US-P GPUB	2004/03/08 11:40	
10	BRS	L10	1	L6 and (compar\$5 with (defective or damaged))	USPA T; US-P GPUB	2004/03/08 11:41	

	Error Definition	Er ro rs
1		0
2		0
3		0
4		0
5		0
6		0
7		0
8		0
9		0
10		0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
11	BRS	L11	114	(secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))	USPA T; US-P GPUB	2004/03/0 8 11:41	
12	BRS	L12	106	L11 not L6	USPA T; US-P GPUB	2004/03/0 8 11:41	
13	BRS	L13	25	L12 and (compar\$5 with (defective or damaged))	USPA T; US-P GPUB	2004/03/0 8 11:45	
14	BRS	L14	0	L13 and ((increas\$7 near3 operation\$3 near3 parameter\$2) with (until near7 fail\$3))	USPA T; US-P GPUB	2004/03/0 8 11:48	
15	BRS	L15	0	L13 and ((inspect\$6) with (until near7 fail\$5))	USPA T; US-P GPUB	2004/03/0 8 11:48	
16	BRS	L16	0	L11 and ((inspect\$6) with (until near7 fail\$5))	USPA T; US-P GPUB	2004/03/0 8 11:49	
17	BRS	L17	0	L11 and ((inspect\$6) with (until near7 (fail\$5 or damaged)))	USPA T; US-P GPUB	2004/03/0 8 11:49	
18	BRS	L18	0	L11 and ((operat\$6) with (until near7 (fail\$5 or damaged)))	USPA T; US-P GPUB	2004/03/0 8 11:51	
19	BRS	L19	21	L11 and (until with (fail\$5 or damaged))	USPA T; US-P GPUB	2004/03/0 8 11:58	
20	BRS	L20	0	L13 and L19	USPA T; US-P GPUB	2004/03/0 8 11:55	

	Error Definition	Er ro rs
11		0
12		0
13		0
14		0
15		0
16		0
17		0
18		0
19		0
20		0

L Number	Hits	Search Text	DB	Time stamp
1	0	("(electron or (charged adj particle) near3 beam\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5)))	USPAT; US-PGPUB	2004/03/08 11:26
2	34	(electron or (charged adj particle) near3 beam\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5)))	USPAT; US-PGPUB	2004/03/08 11:34
3	0	((electron or (charged adj particle) near3 beam\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5))) and (compar\$5 with ((defective or damaged) near2 (chip or circuit or device or die)))	USPAT; US-PGPUB	2004/03/08 11:29
4	1	((electron or (charged adj particle) near3 beam\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5))) and (compar\$5 with (defective or damaged))	USPAT; US-PGPUB	2004/03/08 11:36
5	34	(electron or (charged adj particle) near3 (beam\$2 or irradiation)) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5)))	USPAT; US-PGPUB	2004/03/08 11:35
7	1	((secondary adj electron\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5))) and (compar\$5 with (defective or damaged))	USPAT; US-PGPUB	2004/03/08 11:37
8	1	20020130262.pn.	USPAT; US-PGPUB	2004/03/08 11:37
9	1	((secondary adj electron\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5))) and (compar\$5 with (defective or damaged))	USPAT; US-PGPUB	2004/03/08 11:39
6	8	(secondary adj electron\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5)))	USPAT; US-PGPUB	2004/03/08 11:40
10	1	((secondary adj electron\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5))) and (compar\$5 with (defective or damaged))	USPAT; US-PGPUB	2004/03/08 11:41
11	114	(secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5)))	USPAT; US-PGPUB	2004/03/08 11:41
12	106	((secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))) not ((secondary adj electron\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5)))	USPAT; US-PGPUB	2004/03/08 11:41
13	25	((secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))) not ((secondary adj electron\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5)))) and (compar\$5 with (defective or damaged))	USPAT; US-PGPUB	2004/03/08 11:45
14	0	((secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))) not ((secondary adj electron\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5)))) and (compar\$5 with (defective or damaged)) and ((increase\$7 near3 operation\$3 near3 parameter\$2) with (until near7 fail\$3))	USPAT; US-PGPUB	2004/03/08 11:48

15	0	((((secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))) not ((secondary adj electron\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5)))) and (compar\$5 with (defective or damaged)) ) and ((inspect\$6) with (until near7 fail\$5))	USPAT; US-PGPUB	2004/03/08 11:48
16	0	((secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))) and ((inspect\$6) with (until near7 fail\$5))	USPAT; US-PGPUB	2004/03/08 11:49
17	0	((secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))) and ((inspect\$6) with (until near7 (fail\$5 or damaged)))	USPAT; US-PGPUB	2004/03/08 11:49
18	0	((secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))) and ((operat\$6) with (until near7 (fail\$5 or damaged)))	USPAT; US-PGPUB	2004/03/08 11:51
19	21	((secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))) and (until with (fail\$5 or damaged))	USPAT; US-PGPUB	2004/03/08 11:58
20	0	((((secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))) not ((secondary adj electron\$2) and ((semiconductor near3 chip\$2) with (inspect\$4 near5 defect\$5)))) and (compar\$5 with (defective or damaged)) ) and ((secondary adj electron\$2) and ((semiconductor near3 (chip\$2 or device\$2 or circuit\$2 or die\$2)) with (inspect\$4 near5 defect\$5))) and (until with (fail\$5 or damaged)))	USPAT; US-PGPUB	2004/03/08 11:55